

**PATENT**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

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Confirmation No.: 9849

Group Art Unit: 2818

Examiner: David Vu

Atty. Dkt. No.: 2008.010100  
(formerly 6047-53173)

Serial No.: 09/590,795

Customer No.: 23720

Filed: June 8, 2000

For: METHODS FOR FORMING AND  
INTEGRATED CIRCUIT STRUCTURES  
CONTAINING RUTHENIUM AND  
TUNGSTEN CONTAINING LAYERS

**RESPONSE TO FINAL OFFICE ACTION DATED MARCH 20, 2006**

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This paper is submitted in response to the Final Office Action dated March 20, 2006, for which the two-month date for response is May 20, 2006.

No fees are believed to be due in connection with the present document. However, should any fees be required under 37 C.F.R. §§ 1.16 to 1.21, the Director is authorized to deduct such fees from Williams, Morgan & Amerson, P.C. Deposit Account No. 50-0786/2008.001010.

Reconsideration of the application in view of the following remarks is respectfully requested.